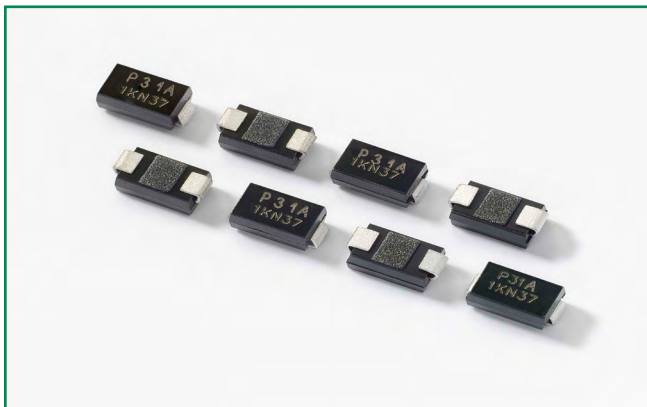


SIDACtor® Series - SMA



Agency Approvals

Agency	Agency File Number
	E133080

Schematic Symbol



Additional Information



Datasheet



Resources



Samples

Description

SIDACtor® SMA Series are designed to protect baseband equipment such as phones, faxes, modems, line cards, CPE and DSL from damaging overvoltage transients.

The series provides a surface mount solution that enables equipment to comply with global regulatory standards.

Features and Benefits

- Low voltage overshoot
- Low on-state voltage
- Does not degrade surge capability after multiple surge events within limit.
- Fails short circuit when surged in excess of ratings
- Low capacitance
- 2nd level interconnect is Pb-free per IPC/JEDEC J-STD-609A.01

Applicable Global Standards

- TIA-968-A*
 - TIA-968-B*
 - ITU K.20/21 Enhanced Level*
 - ITU K.20/21 Basic Level
 - GR 1089 Inter-building*
 - GR 1089 Intra-building
 - IEC 61000-4-5*
 - YD/T 1082
 - YD/T 993
 - YD/T 950
- * Line impedance required to pass operationally

Electrical Characteristics

Part Number	Marking	V_{DRM} @ $I_{DRM} = 5\mu A$	V_S @ 100V/ μs	I_H	I_S	I_T	V_T @ $I_T = 2.2$ Amps	Capacitance @ 1MHz, 2V bias	
		V min	V max	mA min	mA max	A max	V max	pF min	pF max
P0080S1ALRP	P-8A	6	25	50	800	2.2	4	25	35
P0220S1ALRP	P22A	15	32	50	800	2.2	4	10	30
P0300S1ALRP	P03A	25	40	50	800	2.2	4	10	30
P1800S1ALRP	P18A	170	220	150	800	2.2	4	10	30
P2300S1ALRP	P23A	190	260	150	800	2.2	4	10	30
P2600S1ALRP	P26A	220	300	150	800	2.2	4	10	30
P3100S1ALRP	P31A	275	350	150	800	2.2	4	10	30
P3500S1ALRP	P35A	320	400	150	800	2.2	4	10	30
P0080S1BLRP	P-8B	6	25	50	800	2.2	4	20	35
P0220S1BLRP	P22B	15	32	50	800	2.2	4	10	30
P0300S1BLRP	P03B	25	40	50	800	2.2	4	10	30
P1800S1BLRP	P18B	170	220	120	800	2.2	4	10	30
P2300S1BLRP	P23B	190	260	120	800	2.2	4	10	30
P2600S1BLRP	P26B	220	300	120	800	2.2	4	10	30
P3100S1BLRP	P31B	275	350	120	800	2.2	4	10	30
P3500S1BLRP	P35A	320	400	120	800	2.2	4	10	30

Notes:

- Absolute maximum ratings measured at $T_A = 25^\circ C$ (unless otherwise noted).
- Devices are bi-directional (unless otherwise noted).

Surge Ratings

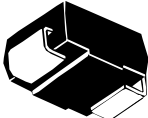
Series	I _{PP}									I _{TSM} 50/60 Hz	di/dt
	0.2x310 ¹	2x10 ¹	8x20 ¹	10x160 ¹	10x560 ¹	5x320 ¹	10x360 ¹	10x1000 ¹	5x310 ¹		
	0.5x700 ²	2x10 ²	1.2x50 ²	10x160 ²	10x560 ²	9x720 ²	10x360 ²	10x1000 ²	10x700 ²		
	A min	A min	A min	A min	A min	A min	A min	A min	A min		
A	20	150	150	90	50	75	75	50	75	20	500
B	-	250	250	90	60	75	75	55	75	25	500

Notes:

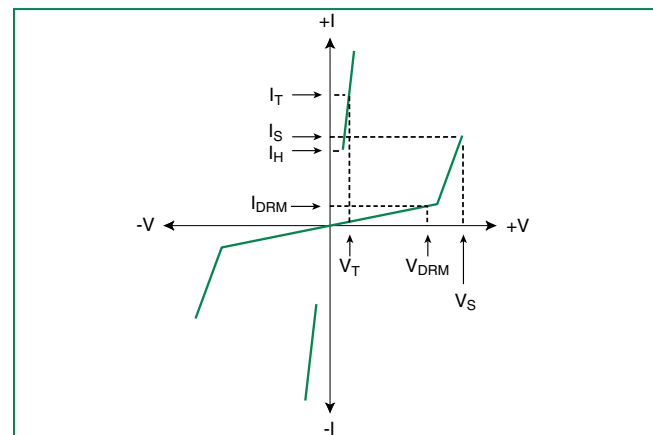
- 1 Current waveform in μs
 2 Voltage waveform in μs

- Peak pulse current rating (I_{PP}) is repetitive and guaranteed for the life of the product.
- I_{PP} ratings applicable over temperature range of -40°C to +85°C
- The device must initially be in thermal equilibrium with -40°C ≤ T_J ≤ +150°C

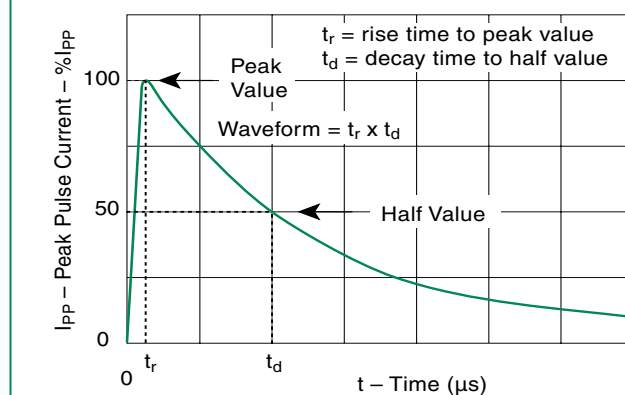
Thermal Considerations

Package	Symbol	Parameter	Value	Unit
DO-214AC 	T_J	Operating Junction Temperature Range	-40 to +150	°C
	T_S	Storage Temperature Range	-65 to +150	°C
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	90	°C/W

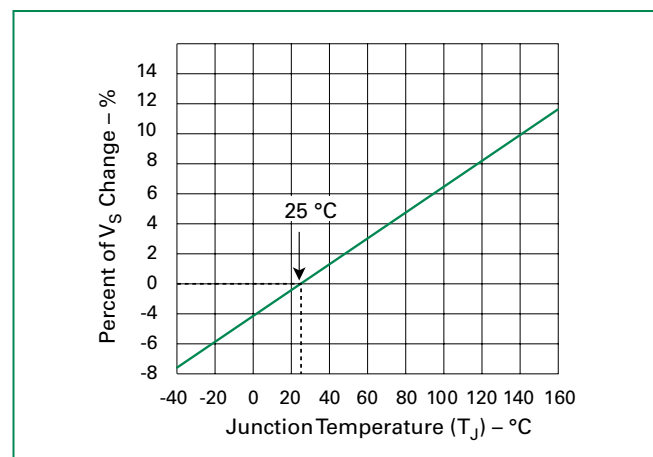
V-I Characteristics



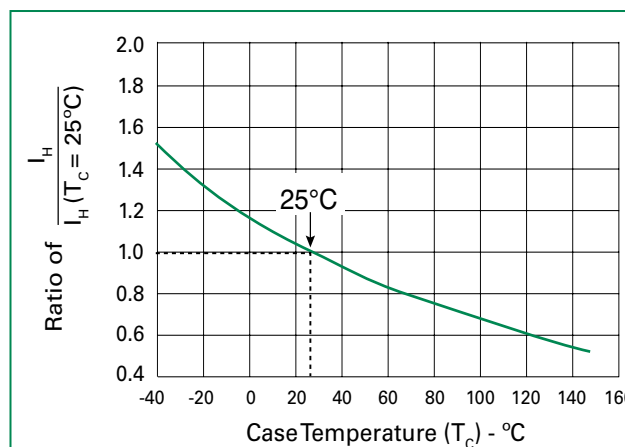
$t_r \times t_d$ Pulse Waveform



Normalized V_S Change vs. Junction Temperature

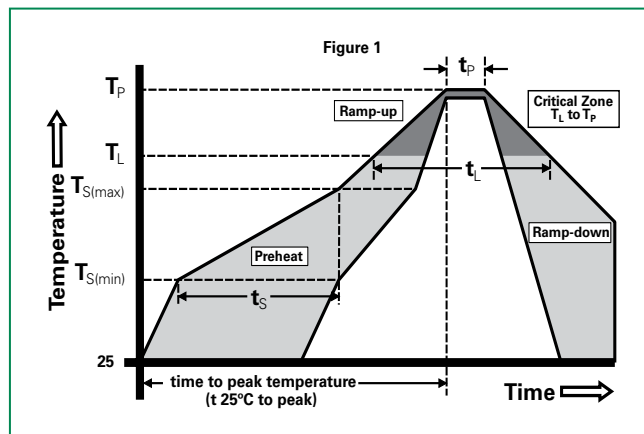


Normalized DC Holding Current vs. Case Temperature



Soldering Parameters

Reflow Condition		Pb-Free assembly (see Fig. 1)
Pre Heat	- Temperature Min ($T_{s(min)}$)	+150°C
	- Temperature Max ($T_{s(max)}$)	+200°C
	- Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max.
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max.
Reflow	- Temperature (T_L) (Liquidus)	+217°C
	- Temperature (t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual PeakTemp (t_p)		30 secs. Max.
Ramp-down Rate		6°C/sec. Max.
Time 25°C to Peak Temp (T_p)		8 min. Max.
Do not exceed		+260°C



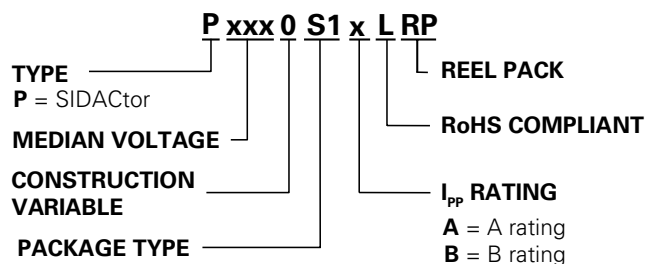
Physical Specifications

Lead Material	Copper Alloy
Terminal Finish	100% Matte-Tin Plated
Body Material	UL recognized epoxy meeting flammability classification 94V-0

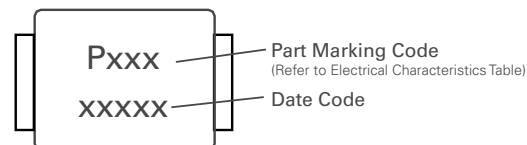
Environmental Specifications

High Temp Voltage Blocking	80% Rated V_{DRM} ($V_{AC, Peak}$) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
Temp Cycling	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A-104
Biased Temp & Humidity	52 V_{DC} (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
High Temp Storage	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
Low Temp Storage	-65°C, 1008 hrs.
Thermal Shock	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
Autoclave (Pressure Cooker Test)	+121°C, 100%RH, 2atm, 24 up to 168 hrs. EIA/JEDEC, JESD22-A-102
Resistance to Solder Heat	+260°C, 30 secs. MIL-STD-750 (Method 2031)
Moisture Sensitivity Level	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

Part Numbering

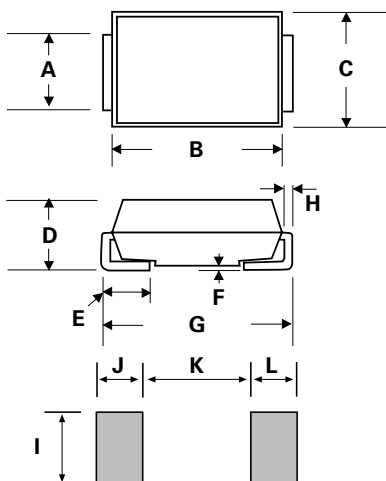


Part Marking



Dimensions

DO-214AC (SMA)



Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.049	0.065	1.250	1.650
B	0.157	0.177	3.990	4.500
C	0.100	0.110	2.540	2.790
D	0.078	0.090	1.980	2.290
E	0.030	0.060	0.780	1.520
F	-	0.008	-	0.203
G	0.194	0.208	4.930	5.280
H	0.006	0.012	0.152	0.305
I	0.070	-	1.800	-
J	0.082	-	2.100	-
K	-	0.090	-	2.300
L	0.082	-	2.100	-

Packing Options

Package Type	Description	Packing Options Quantity	Added Suffix	Industry Standard
S1	DO-214AC Tape & Reel Pack 12mm/13" tape	5000	RP	EIA-481

Tape and Reel Specification — DO-214AC

